Tota	l No	o. of Questions : 8]	$\neg$			
PD4627		27 [6404]-133 [Total No. of Pages	: 2			
B.E. (E & TC) ELECTRONIC PRODUCT DEVELOPMENT (2019 Pattern) (Semester - VII) (Elective - IV) (404185 B)						
Instr		[Max. Marks: fons to the candidates:  Answer Q1 or Q2, Q3 or 4, Q5 or Q6, Q7 or Q8.  Neat diagrams must be drawn wherever necessary.  Figures to the right indicate full marks.  Use of electronic calculator is allowed.  Assume suitable data if necessary.	70			
Q1)			[9]			
	b)	Write short note on the concept of the failure and risk abatement.  OR	[8]			
Q2)	a)	How real time software is embedded in electronic product developme stages.	ent [ <b>9</b> ]			
	b)	What are the different types debugging practices observed in softward development of electronic products.	are [8]			
Q3)	a)	Write short note of routing topology in PCB layout designing.	[9]			
	b)	State and explain fan cooling and force cooling technique in electron product systems.  OR	nic [9]			
Q4)	a)	Explain the grounding & shielding techniques in PCB design. Also explain				
4	b)		[9]			
Á	3)		.ss. [9]			

Write short note on "Good Programming Practices."

Explain the digital to analog conversion techniques.

OR [9]

[9]

<b>Q6</b> )	a)	Compare the conducted EMI and Radiated EMI with example.	[9]
	b)	Explain EMI and EMC issues in details.	[9]
Q7)	a)	Explain the need and various methods of documentation.	[9]
	b)	Explain the effective bill of material with suitable example. Also exp the need of bills of materials.	lain [ <b>8</b> ]
		OR	
Q8)	a)	What are various visual techniques of documentation.	[9]
	b)	Explain the accountability and liability related to records of documentat	ion. [8]
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